

IN THE SPECIFICATION:

Please replace the paragraph appearing at page 1, lines 7-15 with the following:

The present application is related to commonly assigned and co-pending U.S. Patent Application Serial Nos. _____, Attorney Docket No. AUS9-2000-0353-US1 U.S. Patent No. 6,487,515, entitled "Method and Apparatus for Measuring Thermal and Electrical Properties of Thermoelectric Materials," issued on November 26, 2002 and U.S. Patent No. 6,467,951, _____, Attorney Docket No. AUS9-2000-0354-US1 entitled "Probe Apparatus and Method for Measuring Thermoelectric Properties of Materials," issued on October 22, 2002, both filed on _____ and both hereby incorporated by reference.

Please replace the paragraph appearing at page 16, lines 7-17 with the following:

A2
The formation of the probe tip 460 will now be described with reference to Figure 5. The formation of the probe tip 460 is generally described in the incorporated co-pending U.S. Patent Application Serial Nos. _____ (Attorney Docket No. AUS9-2000-0353-US1) and _____ (Attorney Docket No. AUS9-2000-0354-US1) 6,487,515 and 6,467,951. The mechanisms used to create the various layers of the probe, such as deposition and etching, are generally known in the art of semiconductor chip manufacture. However, these mechanisms have not previously been used to create the structure herein described.

Please replace the paragraph appearing at page 2, lines 1-7 with the following:

A3
Development of magnetoresistive (MR) sensors (also referred to as heads) for disk drives in the early 1990's allowed disk drive products to maximize storage capacity with a minimum number of components (heads and disks). Fewer components result in lower storage costs, higher reliability, and lower power requirements for the hard disk drives.